

Silicon Diode in a SOT-323 Plastic Package.

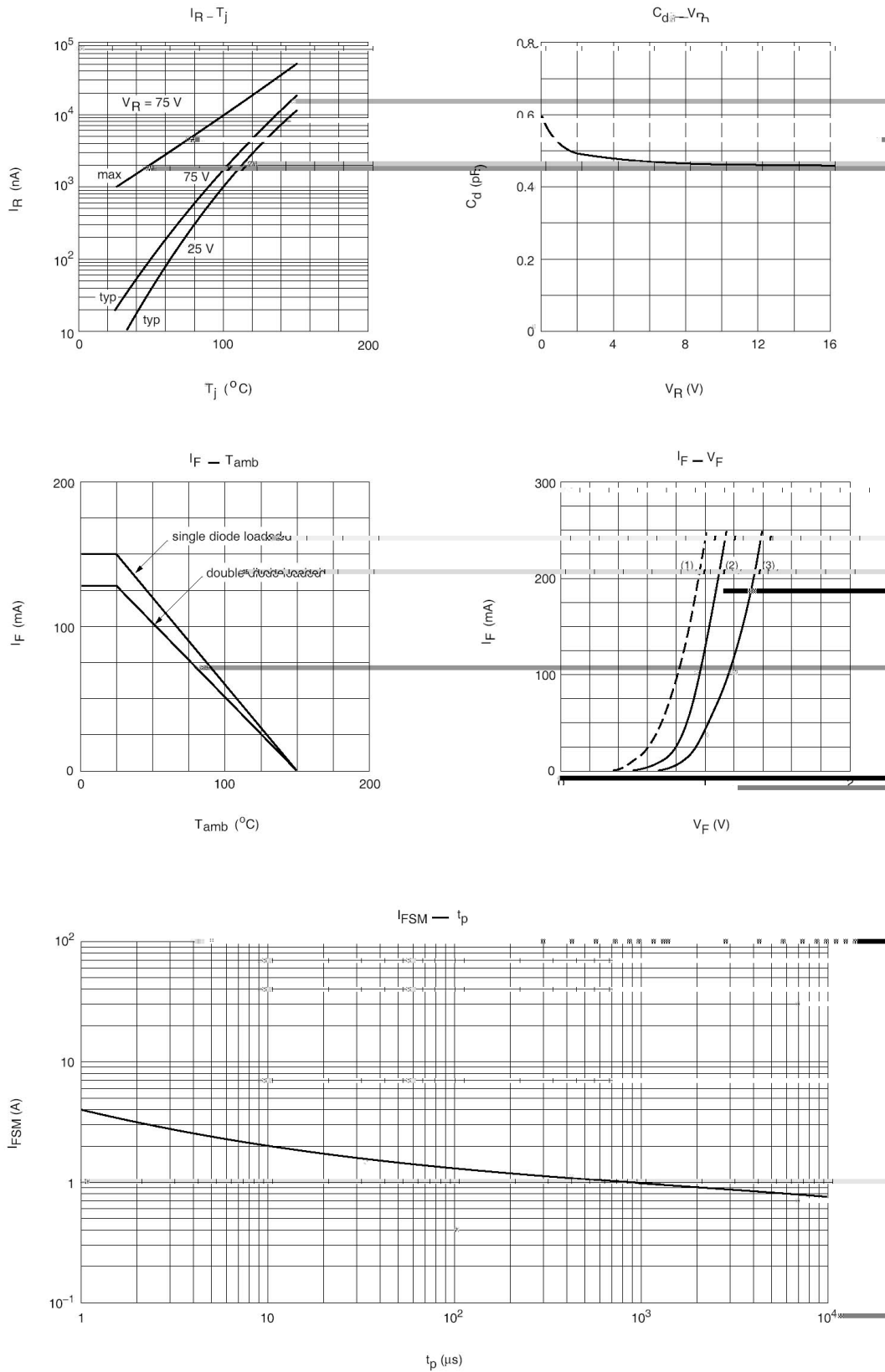
Very small plastic SMD package, High switching speed, High Continuous reverse and Repetitive peak reverse voltage, High Repetitive peak forward current, HF Product.

Applications for High-speed switching. surface mounted circuits.

Parameter	Symbol	Rating	Unit
Repetitive Reverse Voltage	V_{RRM}	85	V
Continuous reverse voltage	V_R	75	V
Continuous forward current	$I_{F(1)}$	150	mA
	$I_{F(2)}$	130	mA
Repetitive peak forward current	I_{FRM}	500	mA
Non-repetitive Peak Forward Current	$I_{FSM(1)}(t=1\text{ S})$	0.5	A
	$I_{FSM(2)}(t=1\text{ mS})$	1.0	A
	$I_{FSM(3)}(t=1\mu\text{S})$	4.0	A
Power Dissipation	P_D	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 +150	

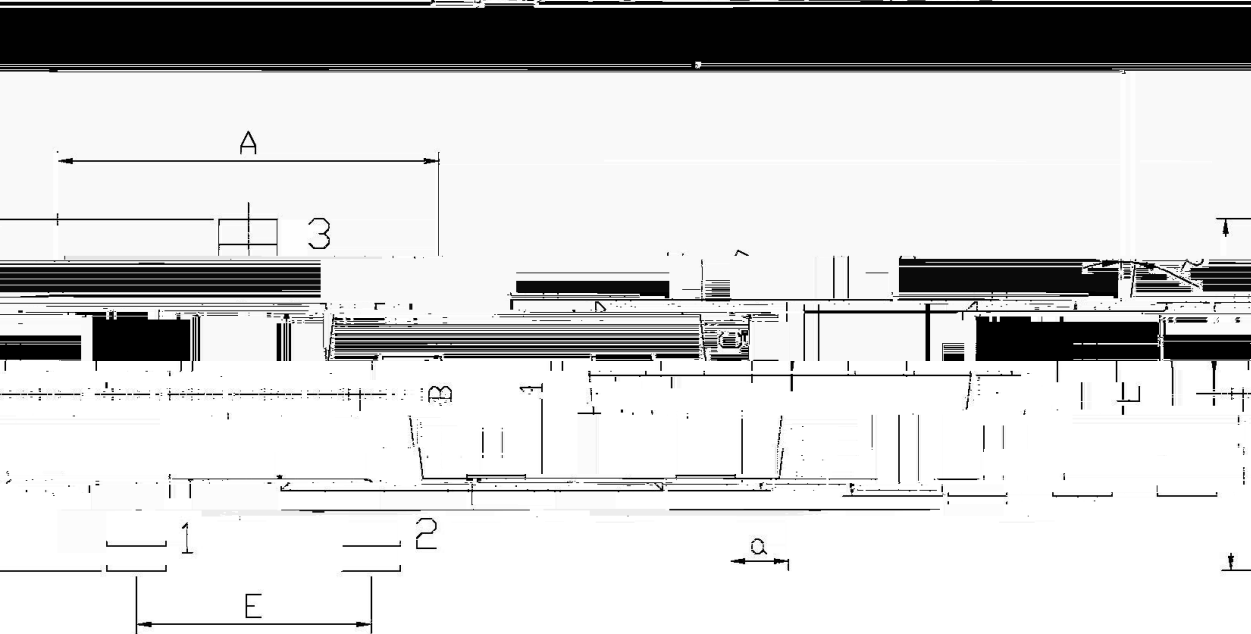
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=1\text{mA}$			715	mV
		$I_F=10\text{mA}$			855	mV
		$I_F=50\text{mA}$			1	V
		$I_F=150\text{mA}$			1.25	V
Instantaneous Reverse Current Total Capacitance	I_R	$V_R=25\text{V}$			30	nA
		$V_R=75\text{V}$			1	μA
		$V_R=25\text{V}$ $T_j=150$			30	μA
		$V_R=75\text{V}$ $T_j=150$			50	μA
Diode capacitance	C_d	$V_R=0$ $f=1\text{MHz}$			1.5	pF
Reverse Recovery Time	t_{rr}	I_R				

I Electrical Characteristic Curve



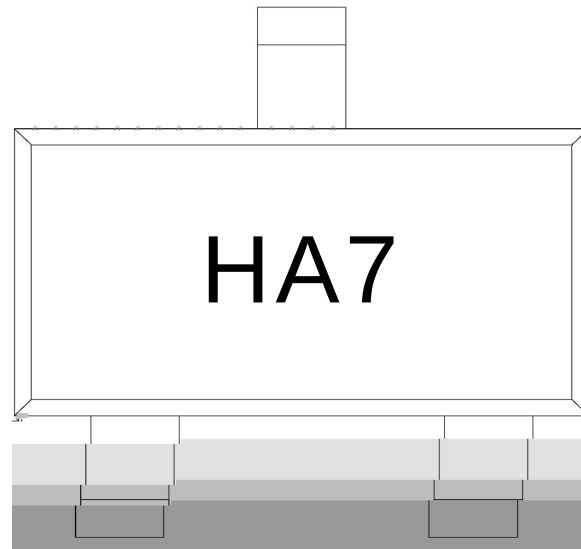
/ Package Dimensions

SOT-323 单位: mm



Dimensions in Millimeter		Dimensions in Millimeter			
Symbol	Min	Max	Symbol		
A	2.00	2.2	L1	0.85	1.15
B	1.20	1.40	a	0.20	0.40
C	1.20	1.40	R	1.5	1.35

/ Marking Instructions



Note:

H: Company Code

A7: Product Type

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**

Note:

- | | | | |
|---|---------|-----------|---|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 5 | 5 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ **Resistance to Soldering Heat Test Conditions**

260 5	10 1 sec.	Temp.:260±5	Time:10±1 sec
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/ **Packaging SPEC.**

/ REEL